

PDFN3030 Plastic-Encapsulate MOSFETS

Features

- $V_{DS}=40V$
- $I_D=30A$
- $R_{DS(on)}@V_{GS}=10V < 12m\Omega$
- $R_{DS(on)}@V_{GS}=4.5V < 18m\Omega$
- Low On-Rdson
- Fast Switching Speedze

Drain-source Voltage

40 V

Drain Current

30 Ampere

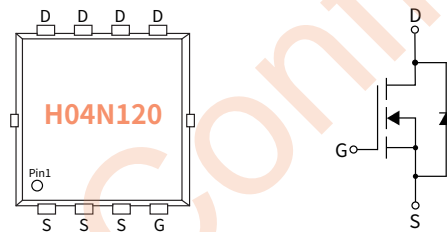
Applications

- DC-DC Converters
- Power Management

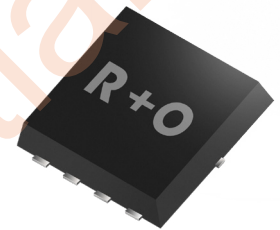
Mechanical Data

- Case: PDFN3030
Molding compound meets UL 94V-0 flammability rating, RoHS-compliant,halogen-free
- Terminals: Solder plated, solderable per MIL-STD-750,Method 2026

Function Diagram



PDFN3030



Ordering Information

PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
PDFN3030	R3	0.0218	5000	10000	80000	13"

Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	VALUE
Drain-source Voltage	V_{DS}	V	40
Gate-source Voltage	V_{GS}	V	± 20
Drain Current	I_D	A	30
Pulsed Drain Current ⁽¹⁾	I_{DM}	A	120
Total Power Dissipation	P_D	W	30
Single pulse avalanche energy ⁽²⁾	EAS	mJ	20
Junction temperature	T_J	°C	-55 ~+150
Storage temperature	T_{stg}	°C	-55 ~+150
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	°C / W	4.2

● Static Parameter Characteristics (Tj=25°C Unless otherwise specified)

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	V	40	—	—
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$	μA	—	—	1.0
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	nA	—	—	± 100
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	V	1.0	1.5	2.5
Static Drain-Source On-Resistance ⁽³⁾	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$	m Ω	—	8	12
		$V_{GS}=4.5V, I_D=8A$		—	11	18

● Dynamic Parameters

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$	pF	—	2049	—
Output Capacitance	C_{oss}			—	124	—
Reverse Transfer Capacitance	C_{rss}			—	108	—

● Switching Parameters

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=20V, I_D=10A, R_{GEN}=3\Omega$	nS	—	6.4	—
Turn-on Rise Time	t_r		nS	—	17.2	—
Turn-off Delay Time	$t_{D(off)}$		nS	—	29.6	—
Turn-off fall Time	t_f		nS	—	16.8	—
Total Gate Charge	Q_g	$V_{DS}=20V, I_D=10A, V_{GS}=10V$	nC	—	36	—
Gate-Source Charge	Q_{gs}		nC	—	8.5	—
Gate-Drain Charge	Q_{gd}		nC	—	7.5	—

● Drian-Source Diode Characteristics

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Diode Forward Voltage	V_{SD}	$I_S=30A, V_{GS}=0V$	V	—	—	1.2
Maximum Body-Diode Continuous Current	I_S	—	A	—	—	30
Reverse recover time	T_{rr}	$I_S=30A, di/dt=100A/us, T_j=25^\circ C$	nS	—	11	—
Reverse recovery charge	Q_{rr}		nC	—	6	—

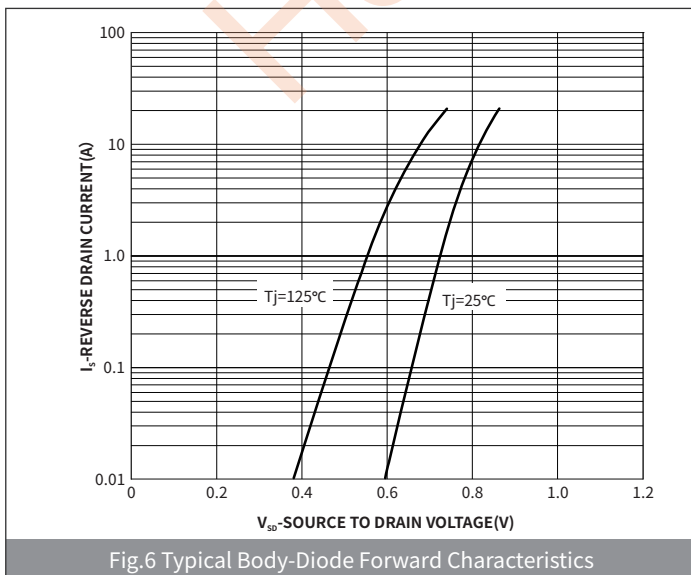
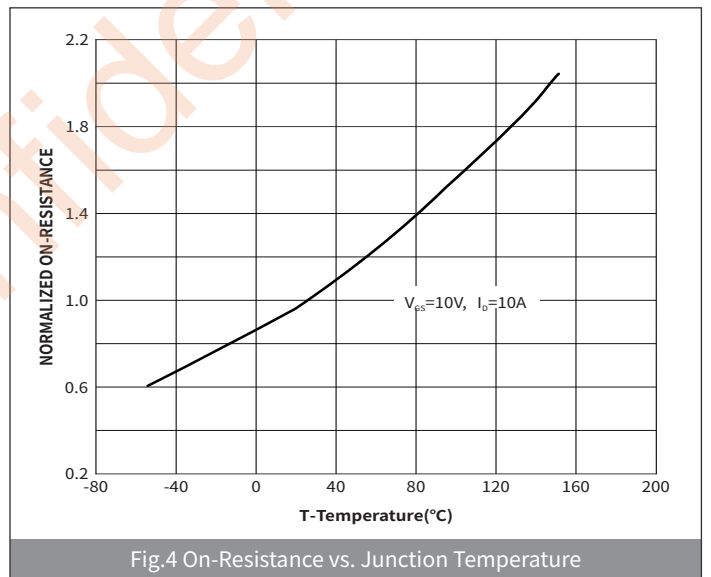
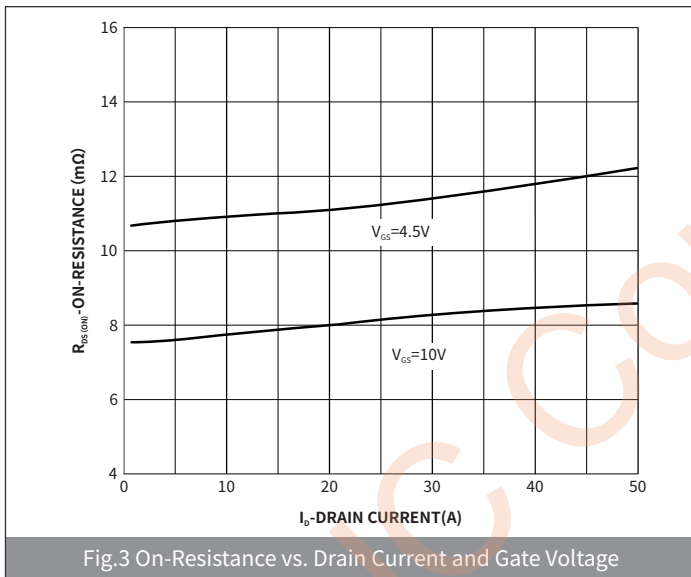
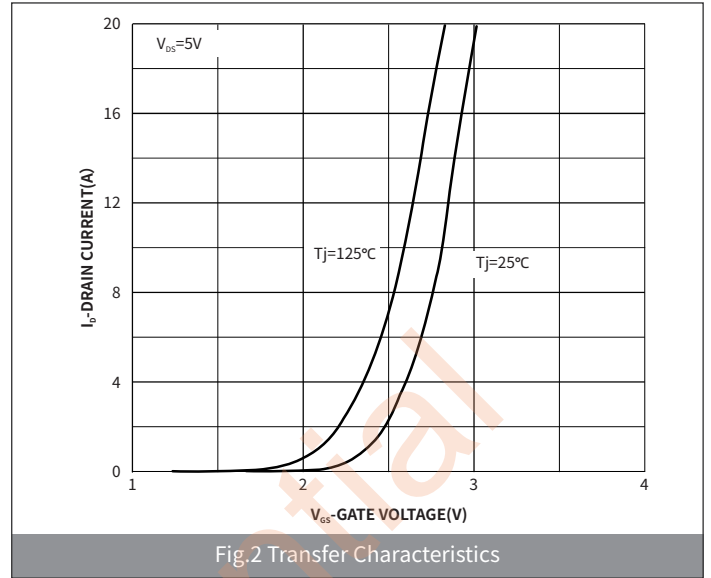
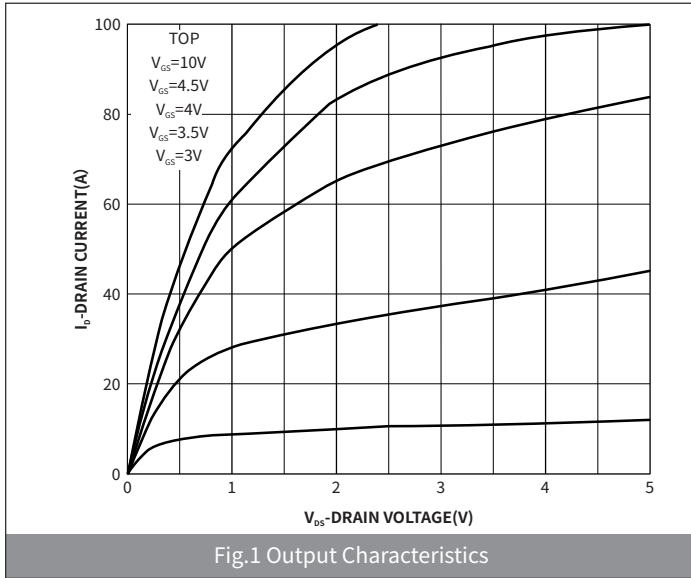
Note :

(1) Repetitive Rating: Pulse width limited by maximum junction temperature.

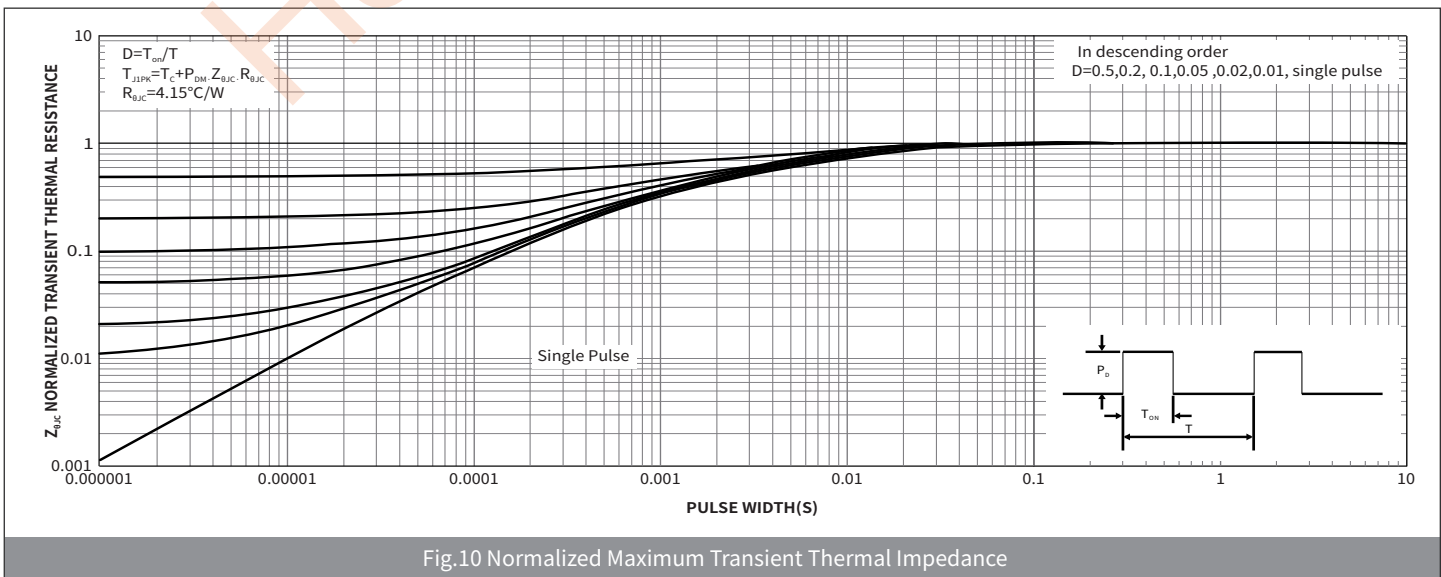
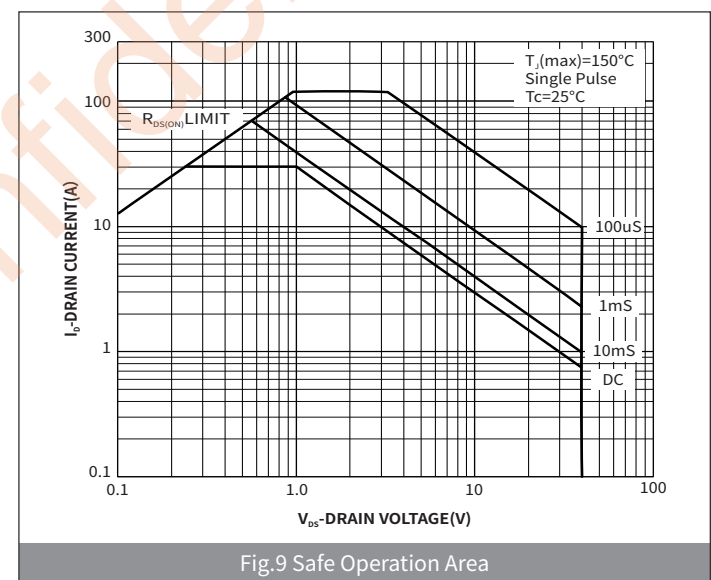
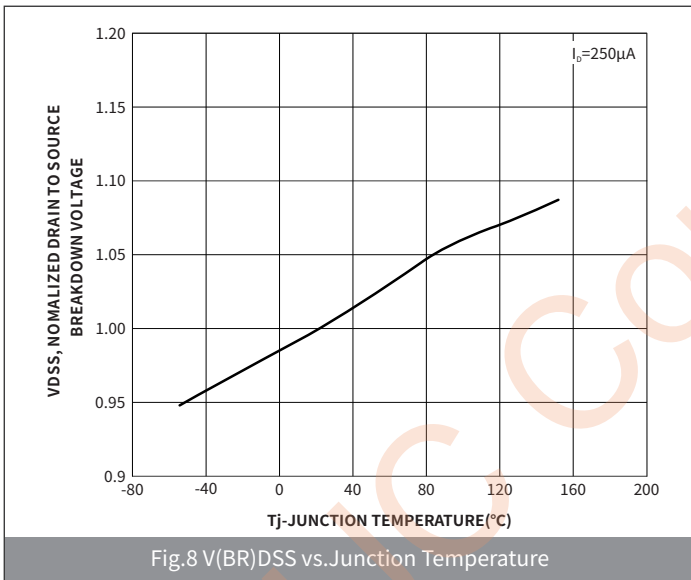
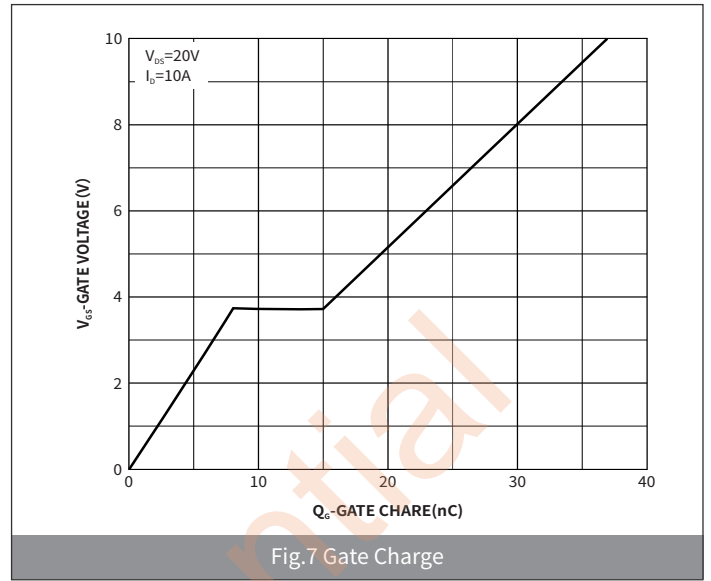
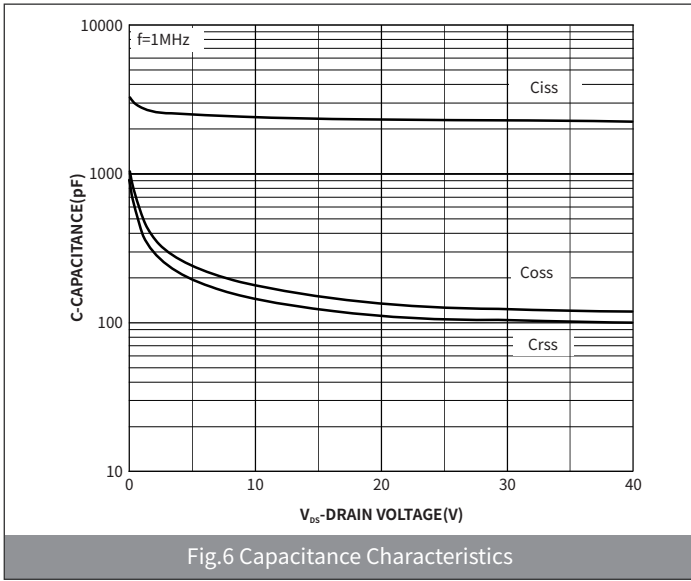
(2) EAS condition : Tj=25°C ,VDD=20V,VG=10V,L=0.5mH,IAS=9A,Rg=25Ω.

(3) Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.

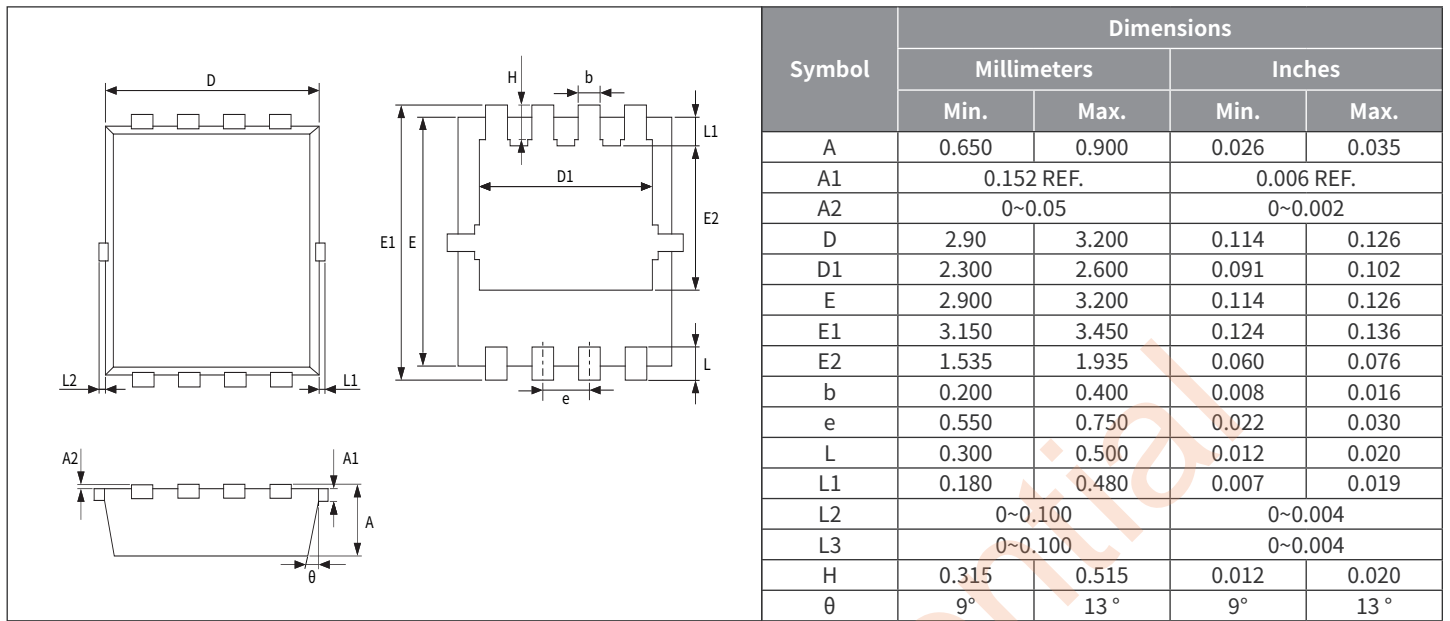
● Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)



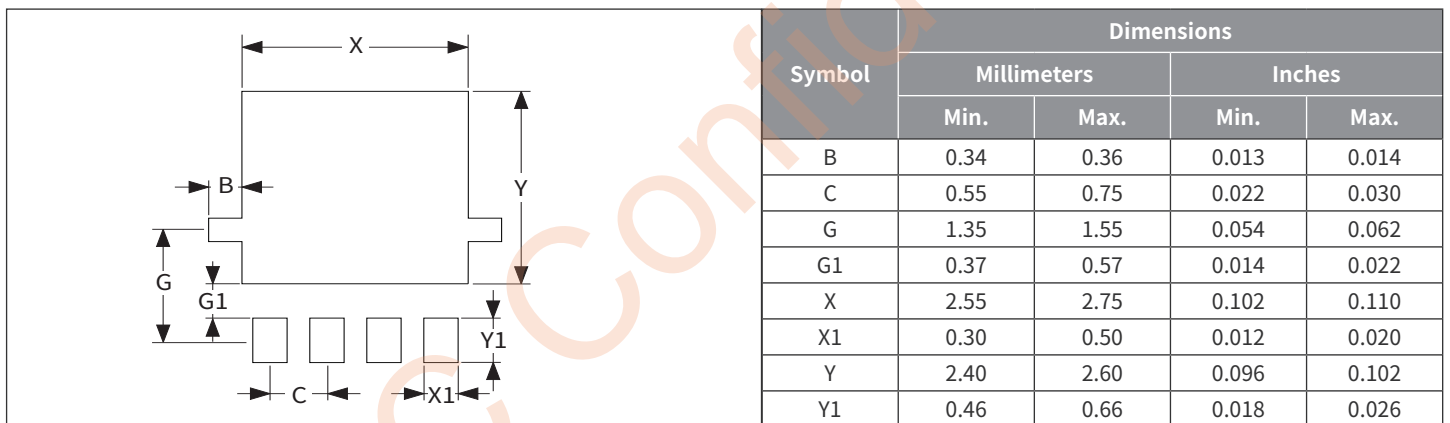
● Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)



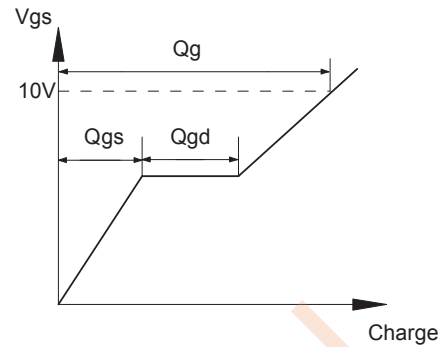
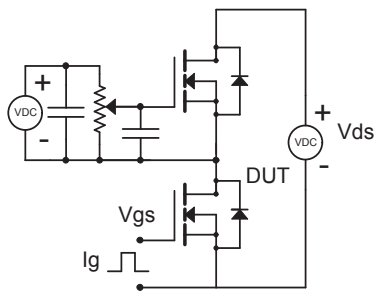
● Package Outline Dimensions (PDFN3030)



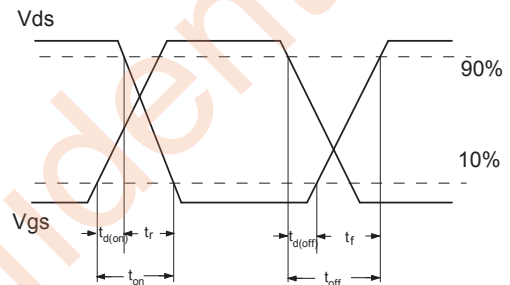
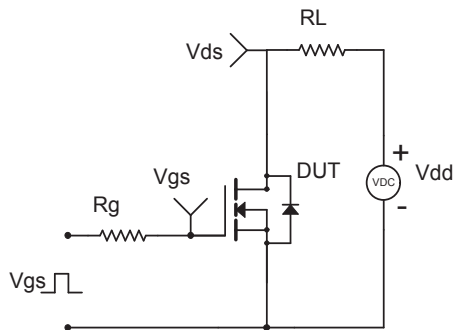
● Suggested Pad Layout



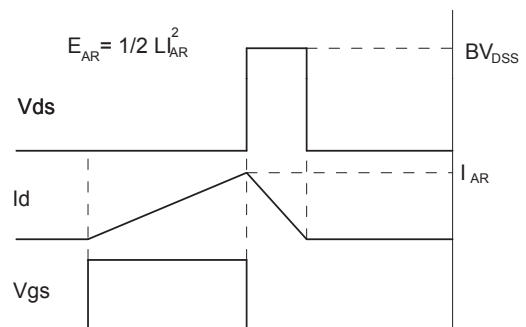
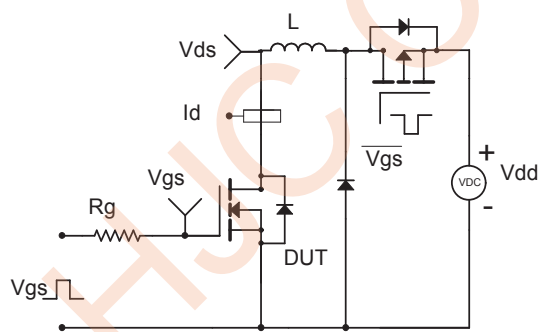
1. Gate Charge Test Circuit & Waveforms



2. Resistive Switching Test Circuit & Waveforms



3. Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



4. Diode Recovery Test Circuit & Waveforms

